Fengjuan Wang

List of Publications by Year
in descending order

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30 papers	214 citations	1307594 7 h-index	1058476 14 g-index
30 all docs	30 docs citations	30 times ranked	117 citing authors

#	Article	IF	Citations
1	A Miniatured Passive Low-Pass Filter With Ultrawide Stopband Based on 3-D Integration Technology. IEEE Microwave and Wireless Components Letters, 2022, 32, 29-32.	3.2	11
2	Optimization of heterogeneous interconnection transmission based on impedance matching for 3-D IC high-frequency application. Microelectronics Journal, 2022, 119, 105317.	2.0	1
3	A miniature TSV-based branch line coupler using Ï€ equivalent circuit model for transmission line. IEICE Electronics Express, 2022, 19, 20210515-20210515.	0.8	2
4	A Miniaturized Wideband Interdigital Bandpass Filter With High Out-Band Suppression Based on TSV Technology for W-Band Application. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2022, 30, 989-992.	3.1	6
5	TSV-Based SIW Bandpass Filter for W-band Mobile Communication Applications. IEICE Electronics Express, 2022, , .	0.8	0
6	Effectiveness of thermal redistribution layer in cooling of <scp>3D ICs</scp>. International Journal of Numerical Modelling: Electronic Networks, Devices and Fields, 2021, 34, e2847.	1.9	1
7	Analytical models of AC inductance and quality factor for TSV-based inductor. IEICE Electronics Express, 2021, 18, 20210319-20210319.	0.8	3
8	Design of compact LC lowpass filters based on coaxial through-silicon vias array. Microelectronics Journal, 2021, 116, 105217.	2.0	2
9	A transformer with high coupling coefficient and small area based on TSV. The Integration VLSI Journal, 2021, 81, 211-220.	2.1	7
10	Compact TSV-Based Hairpin Bandpass Filter for Thz Applications. IEEE Access, 2021, 9, 132078-132083.	4.2	4
11	TSV-based cross-coupled SIW THz bandpass filter with quadrangle components topology. , 2021, , .		1
12	Miniaturized SIW Bandpass Filter Based on TSV Technology for THz Applications. IEEE Transactions on Terahertz Science and Technology, 2020, 10, 423-426.	3.1	35
13	Linearity optimization of current steering DAC based on improved layout topology. , 2019, , .		0
14	LC Low-pass filter based on through-silicon via. , 2019, , .		0
15	Effect of thermal stress on the electrical properties of TSV inductor. , 2019, , .		3
16	Investigation on impact of substrate on low-pass filter based on coaxial TSV. IEICE Electronics Express, 2019, 16, 20180992-20180992.	0.8	5
17	A high-pass filter based on through-silicon via (TSV). IEICE Electronics Express, 2019, 16, 20190098-20190098.	0.8	5
18	Fabrication and measurement of 3D LPF based on coaxial TSV. Electronics Letters, 2019, 55, 102-103.	1.0	6

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19	An Effective Approach of Improving Electrical and Thermo-Mechanical Reliabilities of Through-Silicon Vias. IEEE Transactions on Device and Materials Reliability, 2017, 17, 106-112.	2.0	11
20	An Ultracompact Butterworth Low-Pass Filter Based on Coaxial Through-Silicon Vias. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2017, 25, 1164-1167.	3.1	24
21	Combination of electrical and thermo-mechanical impacts of through-silicon via (TSV) on transistor. , 2017, , .		0
22	Analytical model for 3D IC temperature considering lateral heat conduction. , 2017, , .		1
23	Simple and accurate inductance model of 3D inductor based on TSV. Electronics Letters, 2016, 52, 1815-1816.	1.0	18
24	Thermal management of coaxial through-silicon-via (C-TSV)-based three-dimensional integrated circuit (3D IC). IEICE Electronics Express, 2016, 13, 20151117-20151117.	0.8	2
25	Characteristics of coaxial-annular through-silicon-via in microwave field. , 2016, , .		6
26	Linear CMOS image sensor for bio-microfluidic imaging system. , 2016, , .		0
27	Effects of coaxial through-silicon via on carrier mobility along [100] and [110] crystal directions of (100) silicon. IEICE Electronics Express, 2015, 12, 20150434-20150434.	0.8	5
28	An Effective Approach of Reducing the Keep-Out-Zone Induced by Coaxial Through-Silicon-Via. IEEE Transactions on Electron Devices, 2014, 61, 2928-2934.	3.0	40
29	Capacitance characterization of tapered through-silicon-via considering MOS effect. Microelectronics Journal, 2014, 45, 205-210.	2.0	14
30	Shallow trench isolation structure design for throughâ€silicon vias stress reduction. International Journal of Numerical Modelling: Electronic Networks, Devices and Fields, 0, , .	1.9	1